

Title (en)

ELECTROLYTE AND METHOD FOR ELECTRODEPOSITING COPPER ONTO A BARRIER LAYER

Title (de)

ELEKTROLYT UND VERFAHREN ZUR GALVANISCHEN ABSCHIEDUNG VON KUPFER AUF EINER BARRIERESCHICHT

Title (fr)

ELECTROLYTE ET PROCÉDÉ D'ÉLECTRODÉPOSITION DE CUIVRE SUR UNE COUCHE BARRIÈRE

Publication

**EP 2898121 A1 20150729 (FR)**

Application

**EP 13767028 A 20130828**

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Abstract (en)

[origin: WO2014044942A1] The present invention concerns an electrolyte composition for depositing copper onto semi-conductive substrates covered with a barrier layer. This electrolyte contains a combination of imidazole and 2,2'-bipyridine, used as a suppressor, and thiodiglycolic acid, used as an accelerator. The combination of these additives makes it possible to obtain bottom-up filling on very narrow trenches, typically narrower than 100 nm.

IPC 8 full level

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